

Notice of References Cited	Application/Control No. 10/804,737		Applicant(s)/Patent Under Reexamination ICHITSUBO ET AL.	
	Examiner Monica Lewis		Art Unit 2822	Page 1 of 1

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	V	Charles A. Harper, Electronic Packaging and Interconnection Handbook, 2000, Third Edition, Page 7.20
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.